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PAGE 24/31

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NOV 06 2006

PATENT**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants:	Pierre H. Woerlee Gert Hooft Jisk Holleman	Examiner:	Monica D. Harrison
Serial No.:	10/534,385	Group Art Unit:	2813
Filed:	May 6, 20050	Docket No.:	NL02 1147 US

Title: SILICON LIGHT EMITTING DIODE**Declaration Under 37 C.F.R. § 1.131**

I, Pierre Woerlee, hereby present the following declarations.

Before September 19, 2002, while working with others (Gert Hooft and I being employed at Koninklijke Philips Electronics N.V. and Jisk Holleman being employed at the University of Twente but working in cooperation with Koninklijke Philips Electronics N.V.):

1. I, along with Gert Hooft and Jisk Holleman, invented and designed the structure and method as claimed in the above identified patent application. The invention included a structure and method for creating a radiation-emitting semiconductor device that includes a semiconductor body and a substrate, which silicon-containing semiconductor device has a lateral semiconductor diode which is situated on an insulating layer that separates the diode from the substrate. The lateral semiconductor diode successively comprises a first semiconductor region of a first conductivity type and with a first doping concentration, a second semiconductor region of the first or a second conductivity type opposite to the first conductivity type and with a second doping concentration that is lower than the first doping concentration, and a third semiconductor region of the second conductivity type and with a third doping concentration that is higher than the second doping concentration, the first and the third semiconductor region each being provided with a connection region. During operation, radiation is generated in the second semiconductor region as a result of recombination of charge carriers injected from the first and

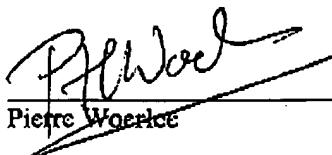
the third semiconductor region in the second semiconductor region, wherein the second semiconductor region comprises a central portion that is surrounded by a further portion the bandgap of which is larger than that of the central portion.

2. I, along with the other inventors, prepared a six-page invention disclosure statement, a true and accurate copy of which is attached hereto as an Exhibit, with pertinent dates intentionally blocked out (each date preceding September 19, 2002) and certain confidential information blacked out and marked "CONFIDENTIAL." The Embodiment of the Invention section on page 4 and accompanying figures of the Exhibit provide further details as to the extent of our invention. The work described above and shown in the Exhibit was performed in the Netherlands. This invention disclosure statement provides details of the efficient light emitting device (LED) in silicon technology that I assisted in inventing and designing.

3. This invention disclosure statement was submitted to the Intellectual Property & Standards Division (formerly known as Corporate Intellectual Property) of Koninklijke Philips Electronics N.V. on February 25, 2002 (before the date of September 19, 2002), and was subsequently used in the preparation of the above-referenced patent application, which was first filed on November 7, 2002 as a European provisional patent application. This patent application entered the United States Patent and Trademark Office as a national stage patent application on May 6, 2005. Diligence was exercised by me, the other inventors, and the Intellectual Property & Standards Division in the searching, drafting, reviewing, and filing of the patent application in the time period between February 25, 2002, and the filing date of November 7, 2002.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Signed this 26 day of October 2006 by:


Pierre Woerlee

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EXHIBIT**NOV 06 2006** *WJS***Invention Disclosure**

Date: 02/25/02-11:48:41	Business Unit: Nat.Lab.	To be filled in by Corporate Intellectual Property Date: 02/25/02-14:07:16 ID-number: 609488
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Names and first names of the inventors:	Sal. nr./ Empil. nr.	Afd/Nr.	Post/Address	Email:	Tel.
Wouterse, PH	37861913	865280	WV-32	phine.wouterse@philips.com	43316
Hooft G.W.	37751811	865330	WB-21	garth.hooft@philips.com	43730
Holleman J.		Univers	PC Box 247, 7500AE Enschede	j.holleman@abtwente.nl	053-4893817

Title of the Invention**Silicon Light Emitting Diode****Summary of the Invention:**

There is a strong demand for an efficient light emitting device (LED) in silicon technology. Recently Silicon LEDs with relatively high efficiency were reported for bulk silicon. In this invention a silicon LED fabricated in Silicon On Insulator (SOI) material is presented. Advantages of SOI are the possibility of band-gap engineering and full dielectric isolation. This enables electron and hole confinement. Furthermore tuning of the wavelength by quantum size effects is possible;

Detailed description of the Invention or annexes: please describe preferred embodiments and their advantages over prior solutions in detail, please include drawings. (See page 2)

Stage and importance of the Invention

a. Stage of the invention?	CONFIDENTIAL	3
b. In what products, processes or systems could the invention be used?	CONFIDENTIAL	4
c. For which other business units of Philips could the invention have relevance?	CONFIDENTIAL	5
d. For which competitors of Philips could the invention have relevance? Why?	CONFIDENTIAL	6
e. For which LTCO(s) could the invention have relevance?	CONFIDENTIAL	7

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Supplemental Information concerning the Invention		
a. Is the invention the result of a cooperation with persons outside Philips? If so, with whom?	CONFIDENTIAL	9
b. Is there, or will there be, an internal report on the invention? If so, please state the number.	CONFIDENTIAL	10
c. Are there, or will there be, other invention disclosures relating to this invention? If so, please state Ref.no.	CONFIDENTIAL	11

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4 d Are there other persons who could give information on the invention?
If so, who?

5 Recommendation inventors to urgency, commercial importance,
and competitors' activities.

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Available Attachments (downloadable via web application)
[silicon_led.doc](#)

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An efficient silicon Light-Emitting Device

P.H. Woerlee, G.W. 't Hooft (Philips Research Labs)

J. Hollenraaij (University of Twente)

State of the Art

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Objective/Problem

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The measures that are proposed to solve the problem, and the resulting advantages

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Embodiment of the invention

An overview of lateral stripe diode fabricated on SOI is presented in figure 2. The left contact (on highly n-doped silicon) injects electrons in the neutral region. The right contact is heavily p-doped silicon, from here holes are injected in the neutral region. In the neutral region electrons and holes recombine, and light emission occurs. The efficiency is increased by the e-h confinement (see fig 2.). The material quality of SOI and its interfaces is excellent (there is a large effort to improve SOI quality for microprocessor fabrication). Hence the non-radiative recombination rate should be low.

An embodiment of the invention is described below. Standard thin-film SOI (Smart-Cut or SIMOX) with Si thickness around 150 nm and buried oxide thickness around 300 nm is used in the device fabrication (fig 3a). In the first step the device isolation (for example shallow trench isolation (STI)) is performed (fig 3b). This is needed to have full dielectric isolation. Furthermore STI is necessary anyhow when CMOS devices are processed with the Si-LED. Then ultra-thin film SOI ($T_{Si} < 10 \text{ nm}$) needs to be fabricated to confine the carriers by bandgap engineering. This can be done either by two anisotropic etching or by two LOCOS like oxidation steps (figure 3c, 3d). The latter procedure is preferred because it is a more robust process for forming of ultra-thin SOI (the oxidation is almost self limiting). Thereafter the n+ and p+ contact areas (3e) are formed by ion implantation (the source/drain implantations of the CMOS technology could be used). The process ends by a standard metallisation (fig. 1).

The fields of application of the invention.

CONFIDENTIAL

References

- [1] L. Pavesi et al., Nature 408, pp.440 (2000).
- [2] W.L. Ng et al., Nature 410, 192-194 (2001).
- [3] M.A. Green et al., Nature 412, 805 (2001).

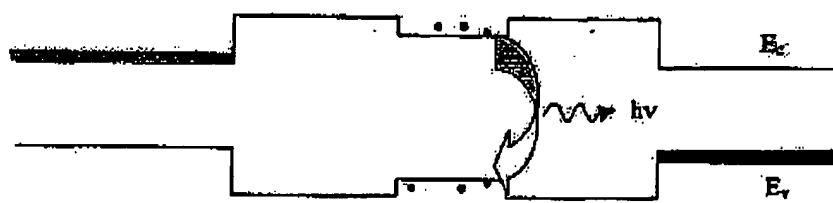


Figure 1: Schematic drawing of band diagram of lateral Si-LED

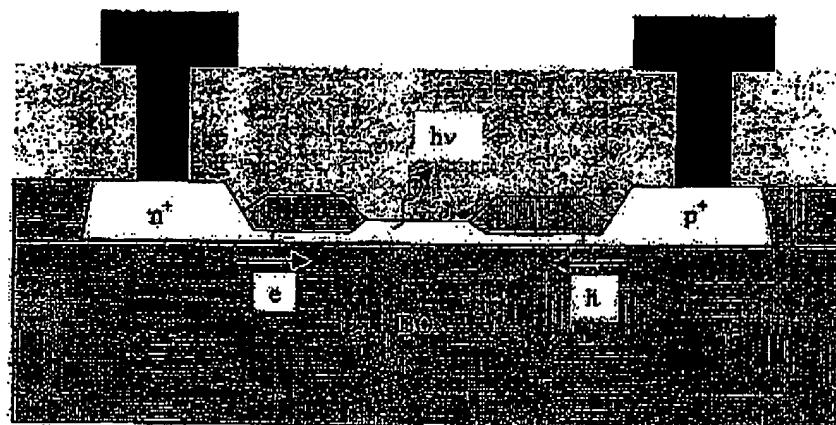
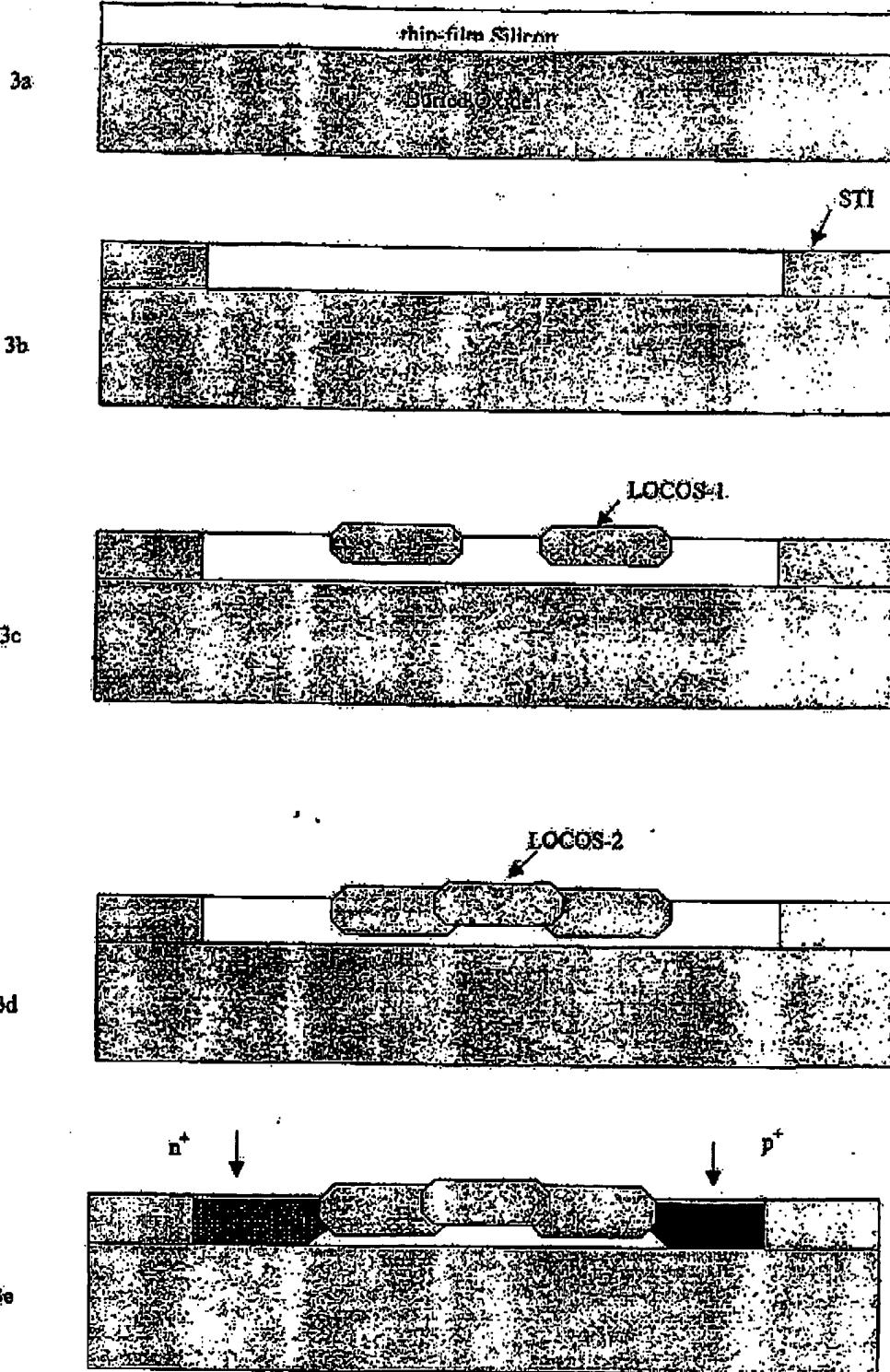


Figure 2: Schematic drawing of SOI-LED



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